Masaki

List of Publications by Year in descending order

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		2258059	2272923	
8	17	3	4	
papers	citations	h-index	g-index	
8	8	8	10	
all docs	docs citations	times ranked	citing authors	

#	Article	IF	CITATIONS
1	Open Defect Detection Not Utilizing Boundary Scan Flip-Flops in Assembled Circuit Boards. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 895-907.	2.5	5
2	A defective level monitor of open defects in 3D ICs with a comparator of offset cancellation type. , 2017, , .		4
3	Open Defect Detection in Assembled Circuit Boards With Built-In Relaxation Oscillators. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 931-943.	2.5	3
4	Electrical Interconnect Test of Solder Joint Part with Boundary Scan Flip Flops and a Built-in Test Circuit. Journal of Japan Institute of Electronics Packaging, 2016, 19, 161-165.	0.1	3
5	On Delay Elements in Boundary Scan Cells for Delay Testing of 3D IC Interconnection. , 2019, , .		1
6	Fault-Aware Dependability Enhancement Techniques for Flash Memories. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2020, 28, 634-645.	3.1	1
7	Fault-Aware Page Address Remapping Techniques for Enhancing Yield and Reliability of Flash Memories. , 2017, , .		O
8	A defect level monitor of resistive open defect at interconnects in 3D ICs by injected charge volume. , 2017, , .		0